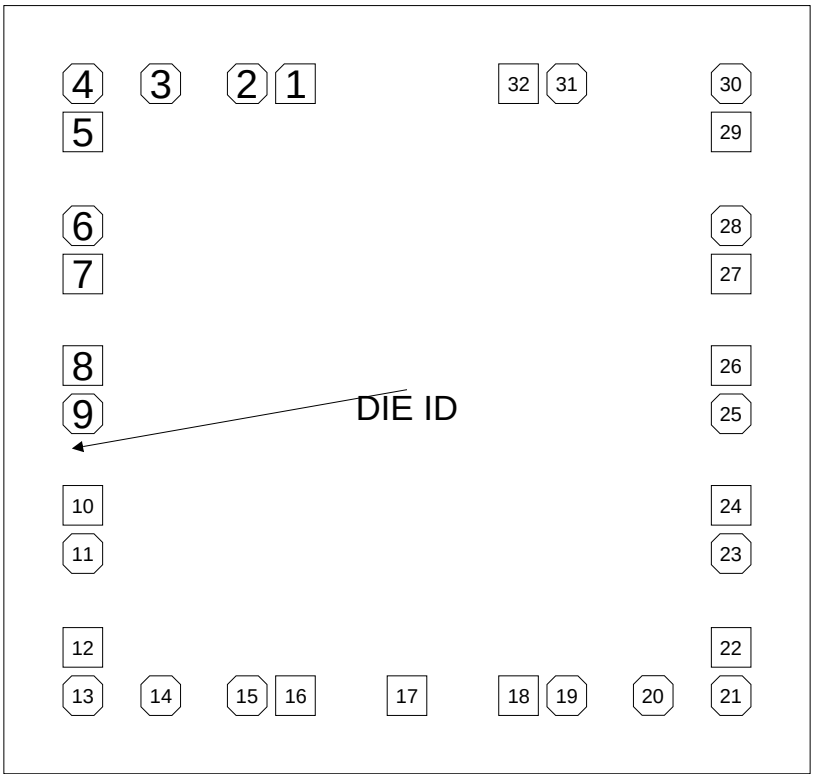
LMP2234A MDC MWC
Quad Micropower, Precision, RRO, Operational Amplifier with CMOS Input

MAR 17, 2008

DIE LAYOUT (A-STEP)



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	LMP2234A	Bond Pad Opening Size (min)	68.60µm x 68.60µm
Die Step	A	Bond Pad Metalization	AL 0.5%CU
Physical Attributes		Passivation	PECVDOX NITRIDE
Wafer Diameter	150mm	Back Side Metal	BAREBACK
Die Size (Drawn)	1397.00µm x 1330.96µm 55.0mils x 52.4mils	Back Side Connection	Floating
Thickness	254µm Nominal		
Min Pitch	158.60µm		
Note: All values are rounded to the nearest micron.			
Special Assembly Requirements:			

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Die Bond Pad Coordinate Locations(A-Step)
(Referenced to die center, coordinates in µm) NC = No Connection, N.U. = Not Used

Signal Name	Pad Number	X/Y Coordinates		Pad Size		
		X	Y	X		Y
Out A	1	-193	530	68	x	68
NC	2	-276	530	68	x	68
NC	3	-426	530	68	x	68
NC	4	-561	530	68	x	68
In A-	5	-561	446	68	x	68
NC	6	-561	284	68	x	68
In A+	7	-561	200	68	x	68
V+	8	-561	41	68	x	68
NC	9	-561	-41	68	x	68
In B+	10	-561	-200	68	x	68
NC	11	-561	-284	68	x	68
In B-	12	-561	-446	68	x	68
NC	13	-561	-530	68	x	68
NC	14	-426	-530	68	x	68
NC	15	-276	-530	68	x	68
Out B	16	-193	-530	68	x	68
NC	17	0	-530	68	x	68
Out C	18	193	-530	68	x	68
NC	19	276	-530	68	x	68
NC	20	426	-529	68	x	68
NC	21	561	-530	68	x	68
In C-	22	561	-446	68	x	68
NC	23	561	-284	68	x	68
In C+	24	561	-200	68	x	68
NC	25	561	-41	68	x	68
V-	26	561	41	68	x	68
In D+	27	561	200	68	x	68
NC	28	561	284	68	x	68
In D-	29	561	446	68	x	68
NC	30	561	530	68	x	68
NC	31	276	530	68	x	68
Out D	32	193	530	68	x	68

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Notes

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